

E1SAA12-30.000M TR



ITEM DESCRIPTION

Quartz Crystal Resonator HC49/UP Short 2 Pad Surface Mount (SMD) 3.2mm Height Metal Resistance Weld Seal 30.000MHz ±50ppm at 25°C, ±100ppm over 0°C to +70°C 12pF Parallel Resonant

ELECTRICAL SPECIFICATIONS

Nominal Frequency	30.000MHz
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over 0°C to +70°C
Aging at 25°C	±5ppm/year Maximum
Load Capacitance	12pF Parallel Resonant
Shunt Capacitance	7pF Maximum
Equivalent Series Resistance	40 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	1mWatt Maximum
Storage Temperature Range	-40°C to +125°C
Insulation Resistance	500 Megaohms Minimum (Measured at 100Vdc)

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

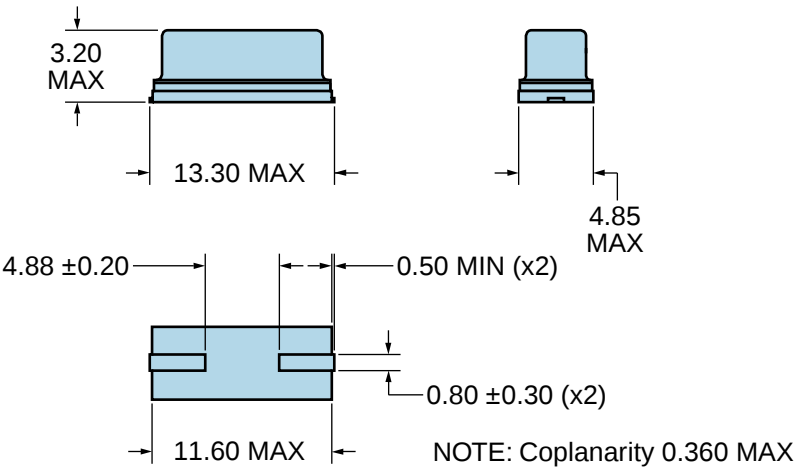
ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

E1SAA12-30.000M TR



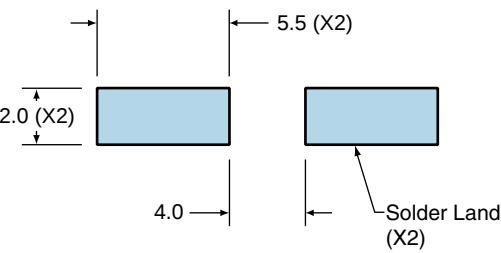
MECHANICAL DIMENSIONS (all dimensions in millimeters)

LINE	MARKING
1	E30.000M E=Ecliptek Designator



Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

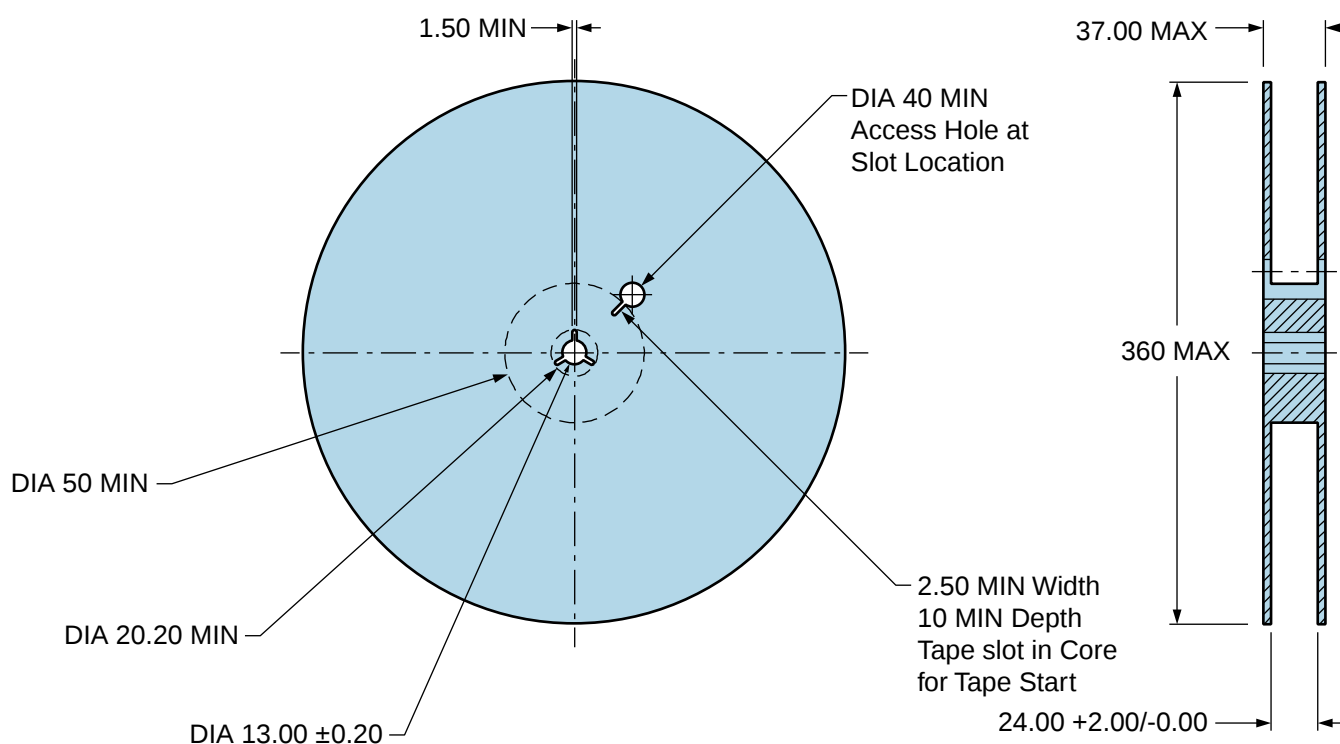
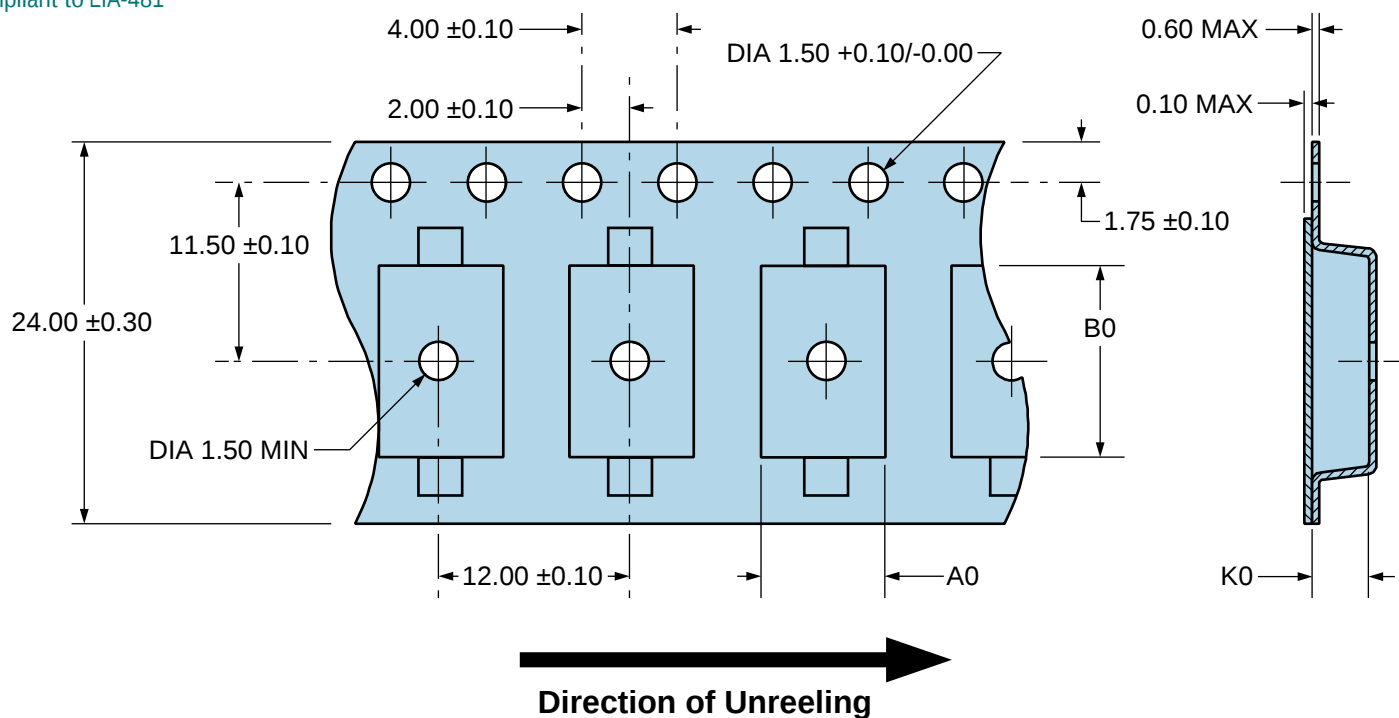
E1SAA12-30.000M TR

Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

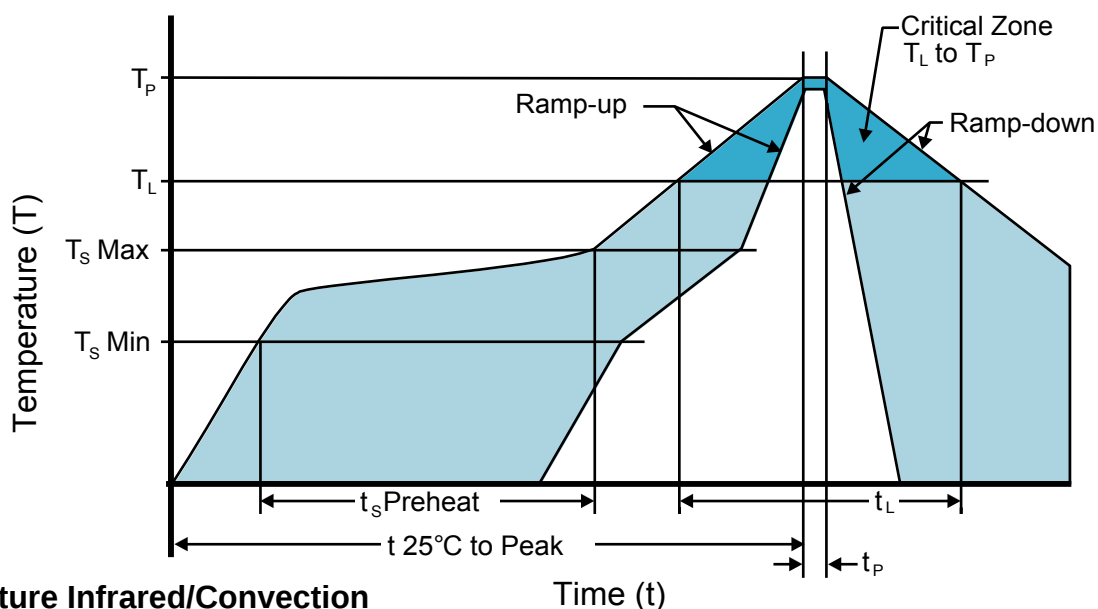
All Dimensions in Millimeters

Compliant to EIA-481



E1SAA12-30.000M TR

Recommended Solder Reflow Methods

**High Temperature Infrared/Convection**

T_s MAX to T_L (Ramp-up Rate) 3°C/Second Maximum

Preheat

- Temperature Minimum (T_s MIN) 150°C
- Temperature Typical (T_s TYP) 175°C
- Temperature Maximum (T_s MAX) 200°C
- Time (t_s MIN) 60 - 180 Seconds

Ramp-up Rate (T_L to T_P) 3°C/Second Maximum

Time Maintained Above:

- Temperature (T_L) 217°C
- Time (t_L) 60 - 150 Seconds

Peak Temperature (T_P) 260°C Maximum for 10 Seconds Maximum

Target Peak Temperature (T_P Target) 250°C +0/-5°C

Time within 5°C of actual peak (t_p) 20 - 40 Seconds

Ramp-down Rate 6°C/Second Maximum

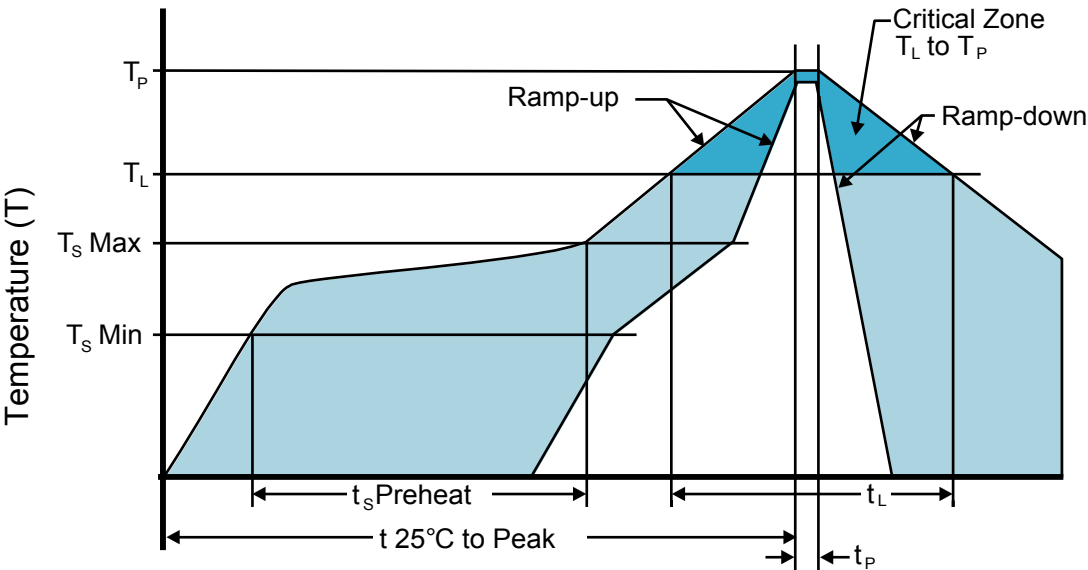
Time 25°C to Peak Temperature (t) 8 Minutes Maximum

Moisture Sensitivity Level Level 1

E1SAA12-30.000M TR



Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 245°C

Ts MAX to TL (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (Ts TYP)	150°C
- Temperature Maximum (Ts MAX)	N/A
- Time (ts MIN)	30 - 60 Seconds
Ramp-up Rate (TL to TP)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (TP)	245°C Maximum
Target Peak Temperature (TP Target)	245°C Maximum 2 Times / 230°C Maximum 1 Time
Time within 5°C of actual peak (tp)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.